Yes No

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE DECLARATION FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled:

A NEW PROCESS FOR PREPARATION OF IMIPENEM

the specification of which	h:		
X is attached hereto;	or		
was filed on	, 20	05 as U.S. Application	Serial No.
I hereby state that I have specification, including the herein.			ne above identified any, specifically referred to
I acknowledge the duty to in accordance with Title			t is material to patentability
	FOREIGN	PRIORITY CLAIM	
foreign application(s) for	r patent or inventor's ation for patent or in	s certificate listed below eventor's certificate have	s Code § 119(a)-(d) of any w and have also identified ving a filing date before tha
No such foreign app	lications have been t	iled _.	
X such foreign applica	tion have been filed	as follows:	
EARLIEST FOREIGN (6 MONTHS FOR DES			
Application Number	Country	Date of Filing	Priority Claimed Under 35 USC 119
10-2003-0088857	Korea	December 9, 2003	X Yes No

				Docke	et No	
LL FOREIGN APPLIC (6 MONTI		IF ANY FILE SIGN) PRIOR				
Application Num		Country			te of Filing	
		*			-	
						,
CLAIM FOR B	ENEFIT OF	EARLIER U.S	S. PROVIS	IONAL AI	PPLICATION	ONS
ereby claim priority be ovisional patent applic			d States Co	ode §119(e), of any U	nited States
			<i>c</i>) 1			
no such U.S. prov	visional appli	cations have be	en filed.			
such U.S. provision	onal applicati	ion have been f	iled as follo	ows:		•
Application	on Number	Date of F	iling		Claimed	
			_		5 USC 119	
				Ycs	No	_
				Yes	s No	
					. N-	
					s No	
CLAIM F	OR BENEFI	T OF EARLIE	R U.S./PC	T APPLIC	ATION(S)	
ereby claim the benefi	it under Title	35. United Sta	ates Code	§120 of the	United Sta	ates
plication(s) listed belo	w and, insof	ar as the subject	t matter of	each of th	e claims of	this
plication is not disclos						
st paragraph of Title 3 formation that is mate	rial to patent	ates Code, 911 ability in accor	dance with	Title 37. C	code of Fed	leral
egulations, §1.56 which	h became av	ailable to me b	etween the	filing date	of the prior	r applicatio
d the national or PCT	'internationa	l filing date of	this applica	tion:		
no such U.S./PCT a	applications h	ave been filed.				
such U.S./PCT appl	lication have	been filed as fo	ollows:			
Application Number	Relat	ionship	Parent App	plication	Date of	f Filing
	Relat	ionship	Parent App	plication	Date of	f Filing

Docket No.	

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

I hereby appoint:

All practitioners at Customer Number 24998

all of **Dickstein Shapiro Morin & Oshinsky LLP**, 2101 L Street NW, Washington, DC 20037-1526, jointly, and each of them severally, my attorneys at law/patent agent(s), with full power of substitution, delegation and revocation, to prosecute this application, to make alterations and amendments therein, to receive the patent, and to transact all business in the U. S. Patent and Trademark Office connected therewith.

Please mail all correspondence to Thomas J. D' Amico, whose address is:

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Please direct telephone calls to Thomas J. D' Amico at (202) 828-4879.

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Docket No.

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·		
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*** *** *** *** **********************	ngtong-Gu. Suwon-City, Republic of K	orea

Full name of third inventor, if any	
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Third inventor's signature	Date
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Docket No.

Full name of fourth inventor, if any			
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Full name of fifth inventor	
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Fifth inventor's signature	Date 2005. 9.23
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